

# MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

[www.msksemi.com](http://www.msksemi.com)

**FEATURES**

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Low reverse leakage
- ◆ Built-in strain relief, ideal for automated placement
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed: 250°C/10 seconds at terminals

**MECHANICAL DATA**
**Case:** DO-214AC

**Terminals:** leads solderable per MIL-STD-750, Method 2026

**Polarity:** Color band denotes cathode end

**Mounting Position:** Any

**Weight:** 0.002 ounce, 0.07 grams

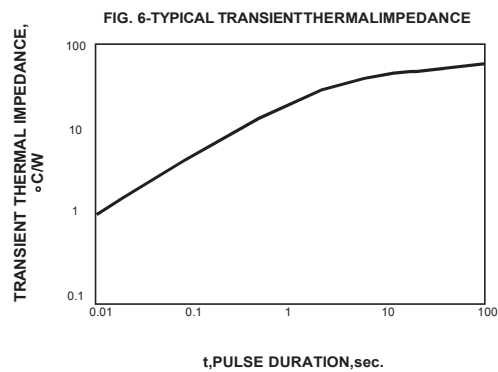
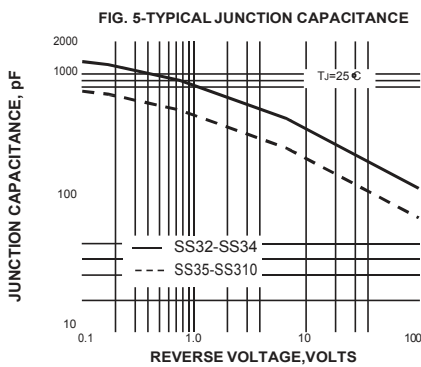
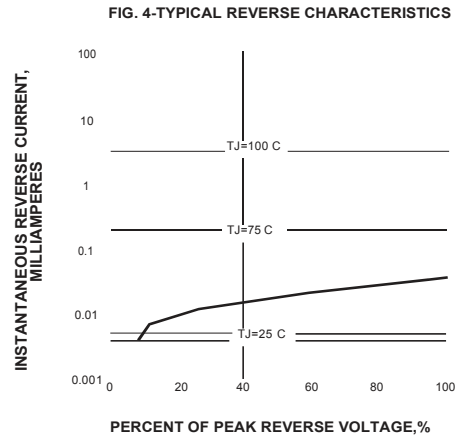
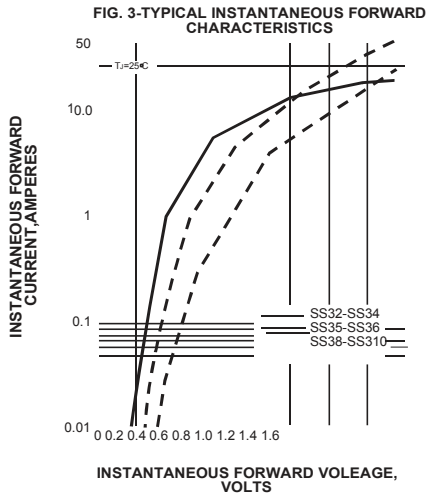
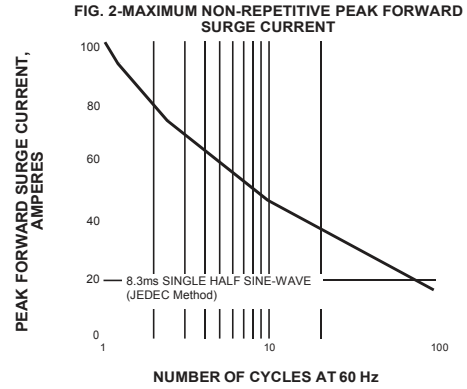
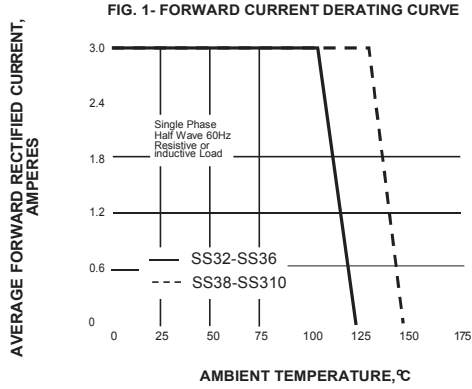
**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

Ratings at 25°C ambient temperature unless otherwise specified.

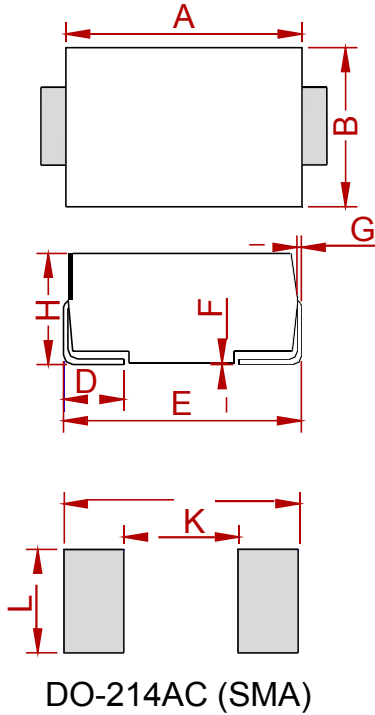
Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

	SYMBOLS	SS22-MS	SS24-MS	SS26-MS	SS210-MS	SS2200-MS	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	20	40	60	100	200	VOLTS
Maximum RMS voltage	$V_{RMS}$	14	28	42	70	140	VOLTS
Maximum DC blocking voltage	$V_{DC}$	20	40	60	100	200	VOLTS
Maximum average forward rectified current at $T_L$ (see fig. 1)	$I_{(AV)}$	2.0					Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50.0					Amps
Maximum instantaneous forward voltage at 2.0A	$V_F$	0.55	0.70	0.85	0.95		Volts
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=100^\circ\text{C}$	$I_R$	0.5				0.2	mA
		10.0		5.0	2.0		
Typical junction capacitance (NOTE 1)	$C_J$	220	180				pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	75.0					°C/W
Operating junction temperature range	$T_J$	-65 to +125			-65 to +150		°C
Storage temperature range	$T_{STG}$	-65 to +150					°C

**Note:** 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 2. P.C.B. mounted with 0.2x0.2" (5.0x5.0mm) copper pad areas



**PACKAGE MECHANICAL DATA**



Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

**REEL SPECIFICATION**

P/N	PKG	QTY
SS22-MS THRU SS2200-MS	SMA	2000

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